

Full Material Declaration for attached parts list

Report generated: 23 December 2015, 12:59 GMT



Diotec Semiconductor AG

DUNS number: 330866844

-, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany

Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2004 [Approved on 23 January 2014, 06:50 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	7.70000%	Nickel	7440-02-0	1.00000%
			Gold	7440-57-5	11.50000%
			Polydimethyl siloxane	63148-62-9	25.00000%
			Silicon	7440-21-3	62.50000%
Die attach	Lead and Lead alloys	0.80000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	45.00000%	Carbon black	1333-86-4	0.30000%
			Epoxy resin 89	26335-32-0	28.30000%
			Quartz sand	60676-86-0	71.40000%
Leadfinish	Tin plating	3.50000%	Copper	7440-50-8	0.30000%
			Silver	7440-22-4	3.20000%
			Tin	7440-31-5	96.50000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	43.00000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
MicroDil/3x3x1.8/1.5	Bridge Rectifier Dual Inline	0.04	g